

ULTRA-LOW PROFILE MICRO ARRAYS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?ZA8

Insulator Material:

FR4

Contact Material:

BeCu

Plating:

Au over 50 μ " (1.27 μ m) Ni

Current Rating:

.8 A per pin

(10 pins powered)

Operating Temp Range:

-55 °C to +105 °C

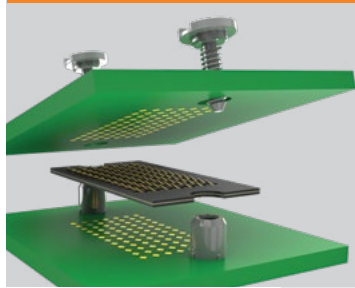
RoHS Compliant:

Yes

Note:

Solder ball parts will come with a pick & place pad.

APPLICATION



HIGH-SPEED CHANNEL PERFORMANCE

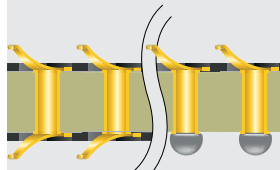
1 mm Stack Height

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

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G b p s

APPLICATION



Dual compression or single compression with solder balls

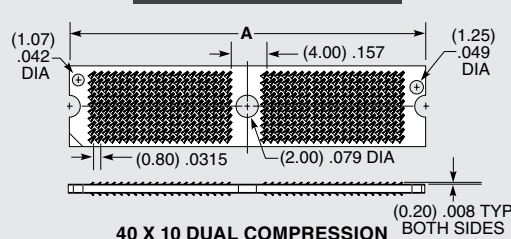
DESIGN FLEXIBILITY

The Z-Ray® platform is highly-customizable:

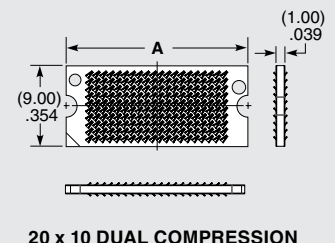
PITCH	≥ 0.65 mm
STACK HEIGHT	0.50 mm to 4.00 mm
DENSITY	Up to 1,200 contacts/square inch
RUGGEDIZING	Latches, Thermal Spreaders, Quick-release Spring Constraints
CONSTRUCTION	Multi-layer FR4 (e.g., Pitch Spreaders)

Note:

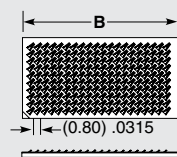
Some lengths, styles and options are non-standard, non-returnable.



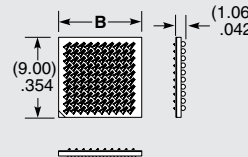
40 X 10 DUAL COMPRESSION



20 X 10 DUAL COMPRESSION



20 X 10 COMPRESSION WITH SOLDER BALLS



10 X 10 COMPRESSION WITH SOLDER BALLS

POSITIONS PER ROW	A	B
-10	(12.50) .492	(9.35) .368
-20	(20.50) .807	(17.35) .683
-30	(31.70) 1.248	N/A
-40	(39.70) 1.563	N/A

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.